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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Kazuaki Ano**

Docket No.: **TI-33183**

Serial No.: **10/017,737**

Examiner: **Lewis, Monica**

Filed: **12/14/2001**

Art Unit: **2822**

For: **Wirebonded Multichip Module**

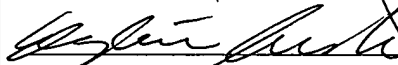
Conf. No.: **8828**

TRANSMITTAL OF FORMAL DRAWINGS

Assistant Commissioner For Patents
Attn: Official Drafts Person
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner For Patents, Washington, DC 20231.


Elizabeth Austin

2/19/2003
Date

Dear Sir:

Submitted herewith is 1 sheet of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Respectfully submitted,



Michael K. Skrehot
Attorney for Applicants
Reg. No.: 36,682

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